

1. (Amended) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;

heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a tin- based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin- based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu; and

heating the solder filler to bond the solder filler to the aluminum body part.

11. ~~8~~ (Amended) The method of claim ~~21~~<sup>10</sup> wherein the solder filler consists of, by weight, 66.5% Sn, 30% Zn, and 3.5% Ni.

~~7~~<sup>13</sup> (Amended) The method of claim ~~22~~<sup>12</sup> wherein the solder filler consists of, by weight, of 80% Zn and 20% Al.

A3 5. ~~11~~ (Amended) A method of applying a solder filler to an aluminum body part comprising the steps of:

forming a filler/flux mixture comprising a tin-based solder filler for aluminum body parts and a fluxing agent wherein the melting point temperature of the solder filler is at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 81% to 85% Sn, 3% to 5% Zn, and 12% to 14% Cu;

applying the filler/flux mixture to the aluminum body part; and

heating the filler/flux mixture to bond the solder filler to the aluminum body part.

A4 ~~17~~<sup>8</sup> (Amended) The method of claim ~~11~~<sup>5</sup> wherein the filler/flux mixture is comprised of by weight about 10% of the fluxing agent and about 90% of the tin-based solder filler.

Please add claims 21-23 as follows:

AS <sup>10</sup>  
21. (New) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;

heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a tin-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the tin-based solder filler consists of, by weight, of 55% to 85% Sn, 12% to 40% Zn, and 3% to 5% Ni, Fe, Cu or Co; and

heating the solder filler to bond the solder filler to the aluminum body part.

<sup>12</sup>  
22. (New) A method of applying a solder filler to an aluminum body part, said method comprising the steps of:

applying a fluxing agent in paste-like form to the aluminum body part;

heating the applied fluxing agent to deoxidize the surface of the aluminum body part;

applying a zinc-based solder filler to the deoxidized surface of the aluminum body part, the melting point temperature of the solder filler being at least 100 degrees C lower than the melting point temperature of the aluminum body part and the zinc-based solder filler consists of, by weight, of 78% to 89% Zn and 11% to 22% Al; and

heating the solder filler to bond the solder filler to the aluminum body part.

<sup>9</sup>  
23. (New) The method of claim 11 wherein the forming step is comprised of providing the tin-based solder filler in the form of a hollow wire and injecting the fluxing agent into the hollow wire.